

APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	[PROCESS AND STRUCTURE FOR SEMICONDUCTOR PACKAGE]
Application Type :	regular, utility
Attorney Docket Number :	9388-US-PA
Correspondence address:	
Customer Number:	31561
	
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Inventors Information:	
<u>Inventor 1:</u>	
Applicant Authority Type:	Inventor
Citizenship:	TW
Name prefix:	Mr.
Given Name:	WEI-CHUN
Family Name:	KUNG
Residence:	
City of Residence:	KAOHSIUNG
Country of Residence:	TW
Address-1 of Mailing Address:	2FL., NO.9, LANE 204, YINGMING RD., LINGYA CHIU
Address-2 of Mailing Address:	
City of Mailing Address:	KAOHSIUNG
State of Mailing Address:	
Postal Code of Mailing Address:	
Country of Mailing Address:	TW
Phone:	
Fax:	
E-mail:	
<u>Inventor 2:</u>	
Applicant Authority Type:	Inventor

Citizenship:	TW
Name prefix:	Mr.
Given Name:	LIAMH-CHENG
Family Name:	CHANG
Residence:	
City of Residence:	KAOHSIUNG
Country of Residence:	TW
Address-1 of Mailing Address:	NO. 16, ALLEY 2, LANE 59, TZENGTZ RD.
Address-2 of Mailing Address:	TZUOYING CHIU
City of Mailing Address:	KAOHSIUNG
State of Mailing Address:	
Postal Code of Mailing Address:	
Country of Mailing Address:	TW
Phone:	
Fax:	
E-mail:	

Attorney Information:

practitioner(s) at Customer Number:

31561



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.